



## **SPECIFICATION**

• Supplier : Samsung electro-mechanics • Samsung P/N : CL10F474ZB8NNNC

• Product : Multi-layer Ceramic Capacitor • Descriptiont : CAP, 470nF, -20/+80%, 50V,Y5V,0603

## A. Samsung Part Number

<u>CL</u> <u>10</u> <u>F</u> <u>474</u> <u>Z</u> <u>B</u> <u>8</u> <u>N</u> <u>N</u> <u>N</u> <u>C</u> ① ② ③ ④ ⑤ ⑥ ⑦ ⑧ ⑨ ⑩ ⑪

1	Series	Samsung Multi-layer Ceramic Capacitor							
2	Size	0603 (inch c	code)	L: 1.6	± 0.1	mm	W:	$0.8 \pm 0.1$	mm
3	Dielectric	Y5V		(8)	Inner e	electrode	Ν	li	
4	Capacitance	<b>470</b> nF			Termin		C	Cu	
⑤	Capacitance	-20/+80 %			Plating	9	S	Sn 100%	(Pb Free)
	tolerance			9	Produc	ct	N	Iormal	
6	Rated Voltage	50 V		10	Specia	ıl	R	Reserved for	future use
7	Thickness	$0.8 \pm 0.1$	mm	11)	Packag	ging	C	ardboard T	ype, 7" reel

## **B. Samsung Reliablility Test and Judgement condition**

	Performance	Test condition					
Capacitance	Within specified tolerance	1kHz±10% 1.0±0.2Vrms					
Tan δ (DF)	0.07 max.						
Insulation	10,000Mohm or 100Mohm·μF	Rated Voltage 60~120 sec.					
Resistance	Whichever is Smaller						
Appearance	No abnormal exterior appearance	Microscope (×10)					
Withstanding	No dielectric breakdown or	250% of the rated voltage					
Voltage	mechanical breakdown						
Temperature	Y5V						
Characterisitcs	(From -30 $^{\circ}$ to 85 $^{\circ}$ , Capacitance change shoud be within -82~+22%)						
Adhesive Strength	No peeling shall be occur on the	500g·F, for 10±1 sec.					
of Termination	terminal electrode						
Bending Strength	Capacitance change : within ±30%	Bending to the limit (1mm)					
		with 1.0mm/sec.					
Solderability	More than 75% of terminal surface	SnAg3.0Cu0.5 solder					
	is to be soldered newly	245±5℃, 3±0.3sec.					
		(preheating: 80~120°C for 10~30sec.)					
Resistance to	Capacitance change : within ±20%	Solder pot : 270±5℃, 10±1sec.					
Soldering heat	Tan δ, IR : initial spec.						

	Performance	Test condition			
Vibration Test	Capacitance change: within ±20%	Amplitude : 1.5mm			
	Tan δ, IR : initial spec.	From 10Hz to 55Hz (return : 1min.)			
		2hours × 3 direction (x, y, z)			
Moisture	Capacitance change: within ±30%	With rated voltage			
Resistance	Tan δ : 0.09 max	40±2℃, 90~95%RH, 500+12/-0hrs			
	IR : 500Mohm or 25Mohm $\cdot \mu$ F				
	Whichever is Smaller				
High Temperature	Capacitance change : within ±30%	With 200% of the rated voltage			
Resistance	Tan δ : 0.09 max	Max. operating temperature			
	IR : 1000Mohm or 50Mohm $\cdot \mu$ F				
	Whichever is Smaller	1000+48/-0hrs			
Temperature	Capacitance change : within ±20%	1 cycle condition			
Cycling	Tan δ, IR : initial spec.	Min. operating temperatur → 25°C			
		→ Max. operating temperature → 25°C			
		5 cycle test			

## C. Recommended Soldering method :

Reflow ( Reflow Peak Temperature : 260+0/-5  $^{\circ}\text{C}\,,$  10sec. Max )

<sup>\*</sup> For the more detail Specification, Please refer to the Samsung MLCC catalogue.